



System Integration & Packaging Innovation for an AI World

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Artificial Intelligence is making its way into life as we know it, with its seemingly limitless scope and power to potentially revolutionize just about everything in our lives. Momentum is strong, so our industry must lockstep and advance technology in pace with application demands. Heterogeneous Integration through SiP for multi-chip devices has become increasingly mainstream, with requirements becoming progressively more sophisticated along the way. System integration is a major focal point. Complex AI devices require innovative SiP technologies that push boundaries to optimize performance capabilities while meeting challenges related to interconnect, power and footprint. Yin Chang will explore the SiP packaging technologies being developed to enable new generations of AI-loaded systems and discuss how our ecosystem can collaborate in key areas such as design and manufacturing to keep innovation flowing and applications on track.